

ST3288P

Component Metallization

Description

ST3288P is a low temperature firing silver conductor paste designed for pad printing solderable electrodes onto a variety of electrical ceramic component devices. The fired film forms a highly adherent bond to many types of substrates, including piezoelectric transducers (PZTs), NTC thermistors, alumina, steatite and porcelain. The metalized electrode is solderable for external lead attachments.

Key Features

- REACH1 and ROHS2 compliant Excellent adhesion Low temperature firing (<700°C) Compatible on piezoelectric transducers (PZT), NTC thermistors, alumina, steatite and porcelain



Typical Properties

Viscosity	15 – 30 kcps, Brookfield RVT, Spindle #14 @ 10 rpm, 25°C
Solids	79.5 ± 1.5%
Resistivity	≤ 3.0 milliohms per square at 25 microns fired film thickness.
Solderability	62Sn/36Pb/2Ag at 230°C 2-3 seconds dip > 99% coverage

Recommended Processing Guide

Drying Temperature	100-150°C for 10-15 minutes
Process Temperature (TDS)	550 - 750C peak temperature Dwell time 8-12 minutes at peak Cycle time of 45-60 minutes Larger parts may require a longer firing profile
Film Thickness	7 - 12 microns
Recommended Thinner	Heraeus RV-252

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Warranty

Material guaranteed to meet specifications for 6 months from date of manufacturing with proper storage.

Storage

Store in a dry location at 5 – 25°C. DO NOT REFRIGERATE. Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

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